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Part Number: 0783150011

Status: Active

Description: 1.00mm (.039") Pitch DDR3 DIMM Socket, Very Low Profile, Vertical, Press-Fit, with Pegs, Black Housing and Latches, 0.76µm (30µ") Gold (Au)Plating, 2.85mm (.112") Compliant Pin Length, 2.60mm (.102") PCB Thickness, 240 Circuits, Lead free



Series image - Reference only

Documents:

Drawing (PDF)

RoHS Certificate of Compliance (PDF)

Product Specification PS-78315-001 (PDF)

General

Product Family	Memory Module Sockets
Series	78315
Component Type	Socket
JEDEC Outline	MO-269
Product Name	DDR3 DIMM

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Color - Resin	Black
Durability (mating cycles max)	25
Entry Angle	Vertical
Function Key	None
Keying to Mating Part	Yes
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	Nylon
PC Tail Length (in)	0.112 In
PC Tail Length (mm)	2.85 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.102 In
PCB Thickness Recommended (mm)	2.60 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.039 In
Pitch - Mating Interface (mm)	1.00 mm
Pitch - Term. Interface (in)	0.039 In
Pitch - Term. Interface (mm)	1.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.76
Plating min: Termination (µin)	15
Plating min: Termination (µm)	0.38
Temperature Range - Operating	-55°C to +85°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	1A
Voltage - Maximum	30V AC (RMS)/DC
Voltage Key	Center

Material Info

Reference - Drawing Numbers

Application Specification	AS-78315-001
Product Specification	PS-78315-001, RPS-78315-001

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free Status
Not Reviewed

China RoHS

Need more information on product environmental compliance?

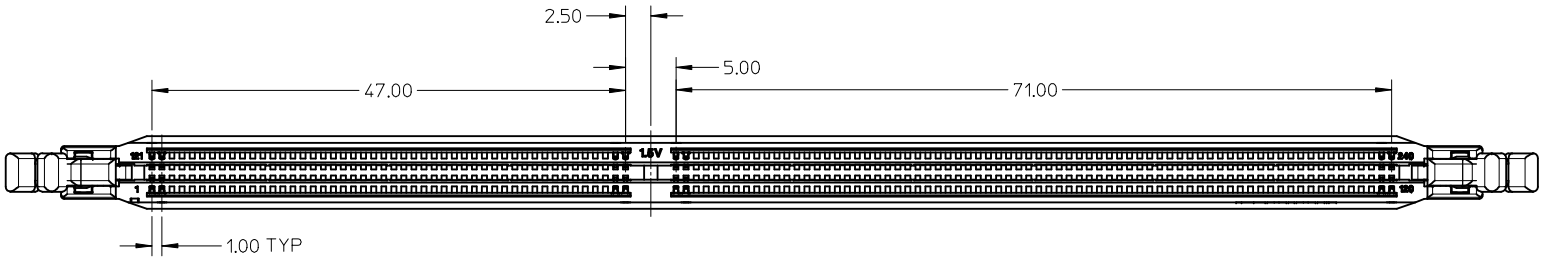
Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

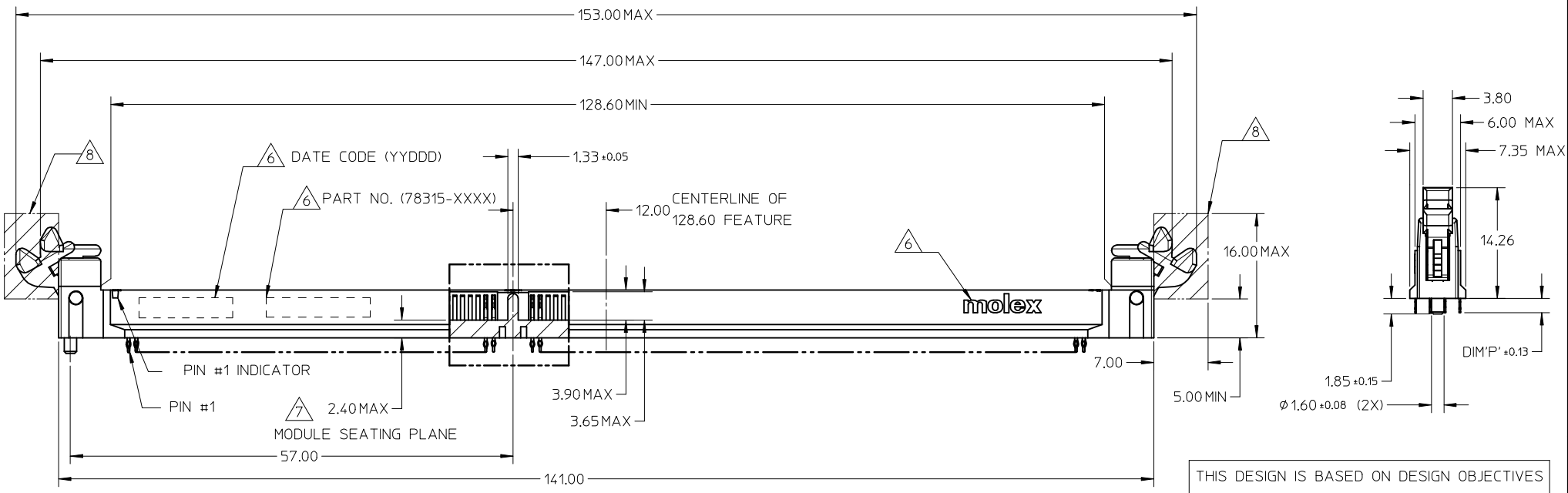
Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
78315Series

Mates With
JEDEC standard 1.27mm modules

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THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

NOTES:
1. MATERIAL:
   HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
   LATCH - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
   TERMINAL - COPPER ALLOY
2. FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
3. PRODUCT SPECIFICATION: PS-78315-001
4. PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
5. CARD SLOT ACCEPTS 1.27 +/- 0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)
6. MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING
7. MODULE SEATING PLANE FROM TOP OF PCB
8. KEEP OUT ZONE RESERVED FOR LATCH

REV	DESCRIPTION	DRWN	CH'KD	APPR	DATE
3	ADDED OPTION EC NO: S2009-0332	CCTEH	CGTAN	SHLENI	2009/05/25 2009/05/25 2009/05/27

QUALITY SYMBOLS
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Ⓒ=0

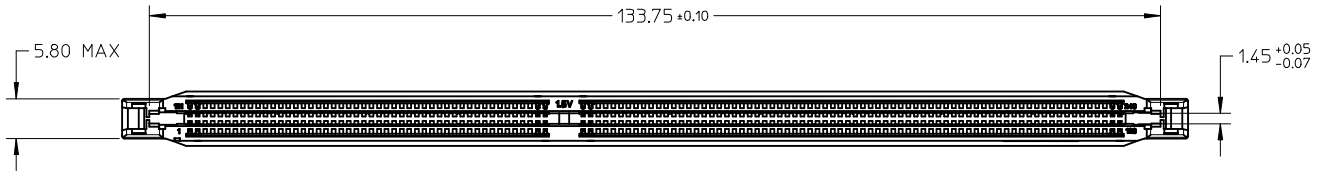
GENERAL TOLERANCES (UNLESS SPECIFIED)

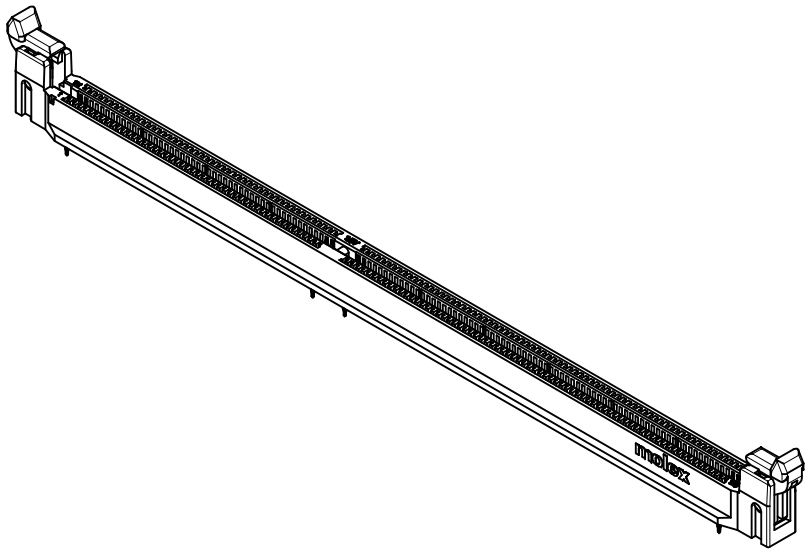
	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

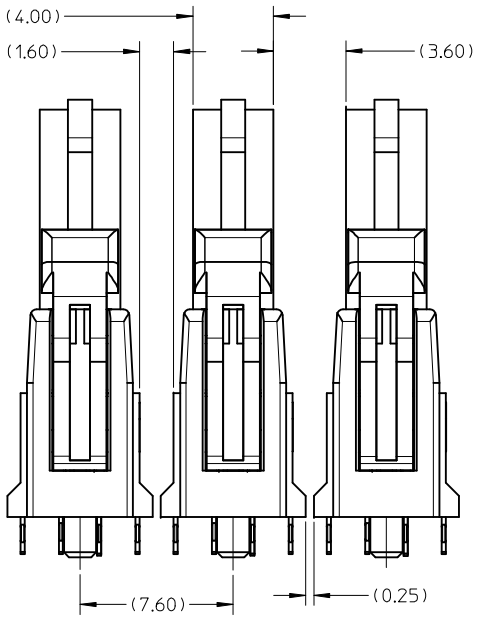
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	NTS
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	CMTEO
DATE	2008/07/17
CHECKED BY	CCTEH
DATE	2008/07/30
APPROVED BY	SHLENI
DATE	2008/08/01
MATERIAL NO.	SEE TABLE
TITLE	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR
	MOLEX INCORPORATED
DOCUMENT NO.	SD-78315-001
SHEET NO.	1 OF 6
SIZE	A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION







MINIMUM ROW TO ROW SPACING RECOMMENDATION
(USING 4.00MM MODULE CARD)

ADDED OPTION	2009/05/25		
EC NO: S2009-0332	2009/05/25		
DRWN:CCTEH	2009/05/27		
CH'KD:CGTAN			
APPR:SHLENI			
DESCRIPTION			
REV			
3			

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	NTS
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	CMTEO
DATE	2008/07/17
CHECKED BY	CCTEH
DATE	2008/07/30
APPROVED BY	SHLENI
DATE	2008/08/01
MATERIAL NO.	SEE TABLE
SIZE	A3

TITLE
DDR3 DIMM (LSP, VLP)
1.00MM PITCH, 240 CKTS
VERTICAL P/F, LOWLLCR

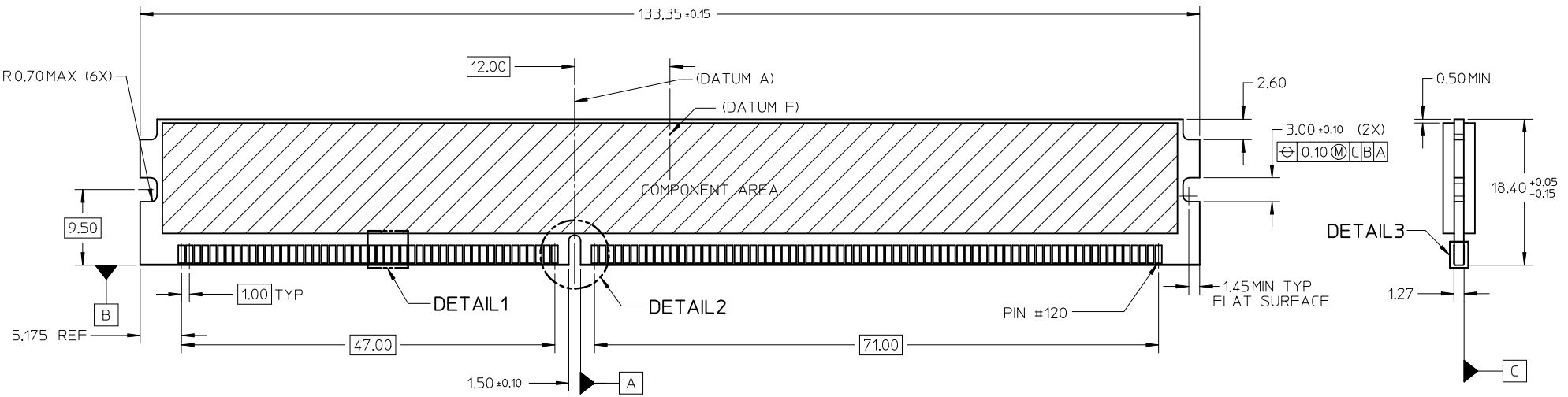
MOLEX INCORPORATED

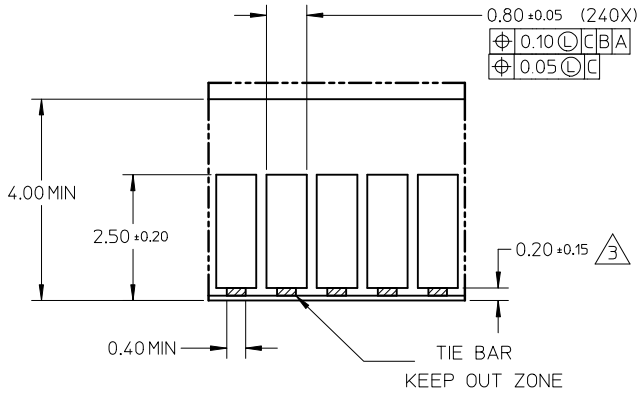
DOCUMENT NO. SD-78315-001

SHEET NO. 2 OF 6

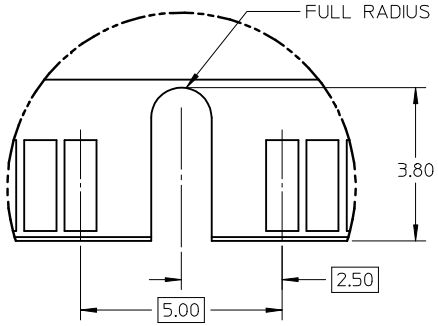
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009MODULE CARD
DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS
(JEDEC MO-269, ISSUE A, 12/05)

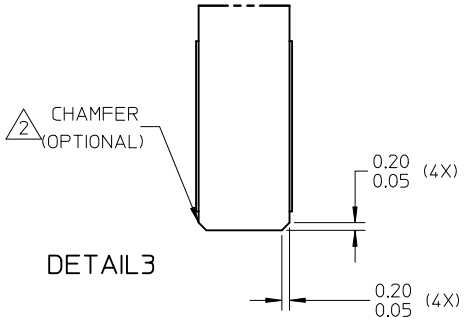




DETAIL1



DETAIL2



DETAIL3

NOTES:
1. RECOMMENDED PLATING FOR CONTACT PADS:
PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN
OVER 2.00 MICROMETERS NICKEL
ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING
OVER 2.00 MICROMETERS NICKEL MUST
USE AN ELECTRONIC CONTACT GRADE
CORROSIVE BARRIER LUBRICANT
2. CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
3. LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE
SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

REV	DESCRIPTION	DRWN	CH'KD	APPR	DATE
3	ADDED OPTION EC NO: S2009-0332	CTEH	CGTAN	SHLENI	2009/05/25 2009/05/25 2009/05/27

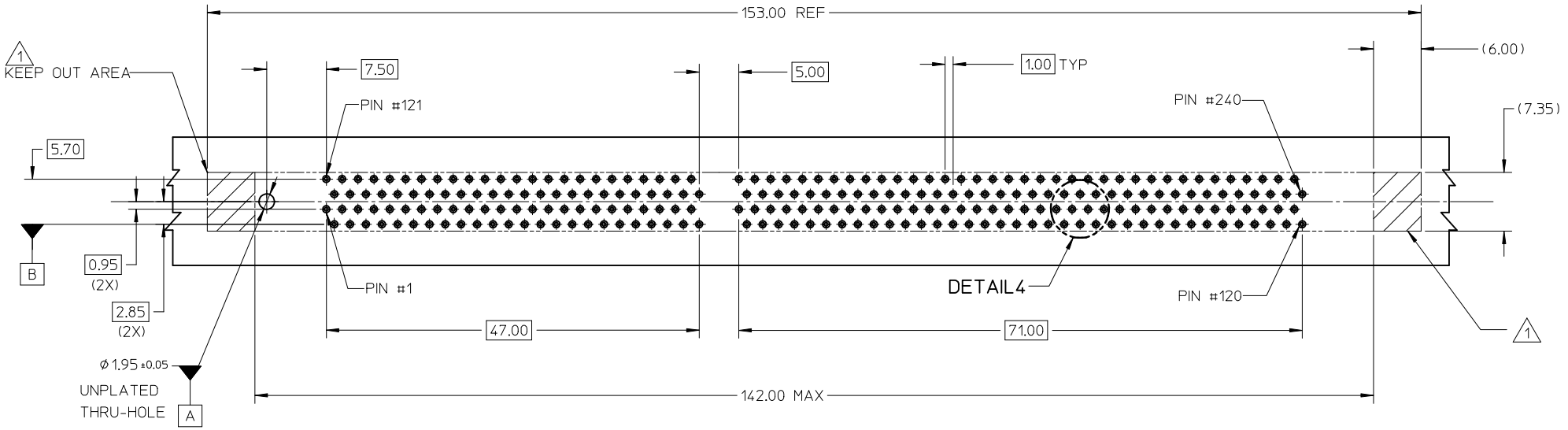
QUALITY SYMBOLS
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Ⓒ=0

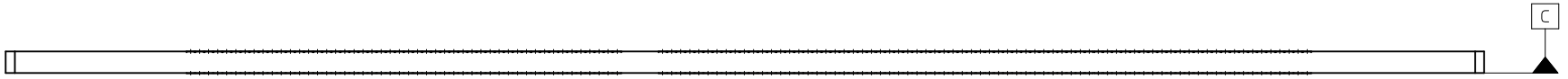
GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

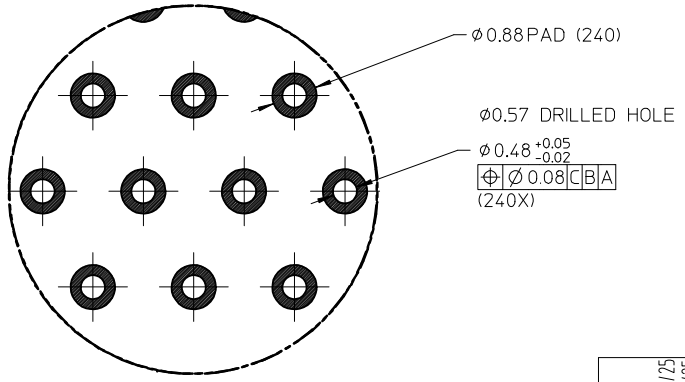
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	NTS
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	CMTEO 2008/07/17
CHECKED BY / DATE	CCTEH 2008/07/30
APPROVED BY / DATE	SHLENI 2008/08/01
MATERIAL NO.	SEE TABLE
TITLE	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR
	MOLEX INCORPORATED
DOCUMENT NO.	SD-78315-001
SHEET NO.	3 OF 6
SIZE	A3

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DETAIL4

NOTES:
1. KEEPOUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

REV	DESCRIPTION	
3	ADDED OPTION	2009/05/25
	EC NO: S2009-0332	2009/05/25
	DRWN:CCTEH	2009/05/27
	CH'KD:CGTAN	
	APPR:SHLENI	

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

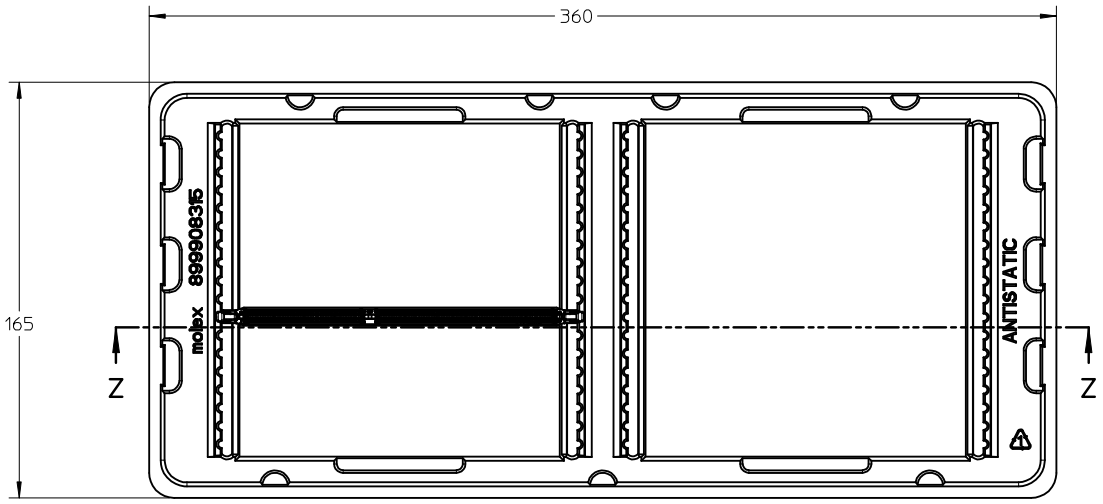
	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

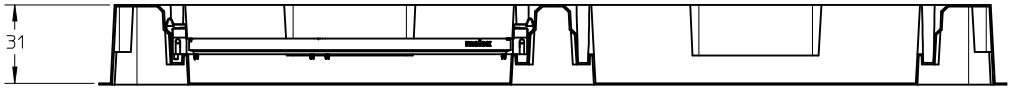
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	NTS
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	CMTEO
DATE	2008/07/17
CHECKED BY	CCTEH
DATE	2008/07/30
APPROVED BY	SHLENI
DATE	2008/08/01
MATERIAL NO.	SEE TABLE
TITLE	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR
	MOLEX INCORPORATED
DOCUMENT NO.	SD-78315-001
SHEET NO.	4 OF 6
SIZE	A3

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VIEW FOR PACKAGING TRAY





SECTION Z-Z

NOTE:

1. NO. OF CAVITY - 18 X 2 =36

REV	DESCRIPTION	
3	ADDED OPTION	
	EC NO: S2009-0332	2009/05/25
	DRWN:CCTEH	2009/05/25
	CH'KD:CGTAN	2009/05/27
	APPR:SHLENI	

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	NTS
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	CMTEO
DATE	2008/07/17
CHECKED BY	CCTEH
DATE	2008/07/30
APPROVED BY	SHLENI
DATE	2008/08/01
MATERIAL NO.	SEE TABLE
SIZE	A3

TITLE: DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR

MOLEX INCORPORATED

DOCUMENT NO. SD-78315-001

SHEET NO. 5 OF 6

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PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	
				CONTACT AREA	TAIL AREA
78315-0001	CENTER (1.5V)	1.85	2.40	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE
78315-0201				0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN/LEAD (BRIGHT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE
78315-0011		2.85	2.60	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE

REV	DESCRIPTION	
3	ADDED OPTION	
	EC NO: S2009-0332	2009/05/25
	DRWN:CCTEH	2009/05/25
	CH'KD:CGTAN	2009/05/27
	APPR:SHLENI	

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: CMTEO DATE: 2008/07/17
CHECKED BY: CCTEH DATE: 2008/07/30
APPROVED BY: SHLENI DATE: 2008/08/01
MATERIAL NO.: SEE TABLE

TITLE: DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR

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DOCUMENT NO.: SD-78315-001
SHEET NO.: 6 OF 6

SIZE: A3

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